

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-9 (canceled).

Claim 10 (currently amended): A substrate of a support element, the substrate comprising:

- (a) an insulating material having a first surface;
- (b) a defective pattern of conductors on the first surface;
- (c) a wire bond slot forming an opening through the substrate extending from the first surface to a second surface, wherein the wire bond slot is associated with the defective pattern of conductors; and
- (d) a cover member attached to the substrate on the second surface so as to cover at least a portion of the wire bond slot, wherein the cover member does not comprise a functional die.

Claim 11 (original): The substrate of claim 10, wherein the cover member comprises self-adhesive tape.

Claim 12 (original): The substrate of claim 10, wherein the cover member comprises a defective die.

Claim 13 (original): The substrate of claim 10, wherein the cover member covers from about 80% to about 90% of the wire bond slot.

Claims 14-22 (canceled).

Claim 23 (currently amended): A substrate of a support element, the substrate comprising:

- (a) a first surface having a pattern of conductors;
- (b) a second surface having a die attach area with defective electrical circuitry;
- (c) a wire bond slot forming an opening through the substrate extending from the first surface to the second surface, wherein the wire bond slot is associated with the die attach area having defective electrical circuitry; and
- (d) a cover member attached to the substrate on the second surface so as to cover a majority of the opening formed by the wire bond slot, wherein the cover member does not comprise a functional die.

Claims 24-35 (canceled).

Claim 36 (previously presented): The substrate of claim 10, wherein the cover member covers from about 70% to about 98% of the opening formed by the wire bond slot.

Claims 37-38 (canceled)

Claim 39 (new): A substrate of a support element, the substrate comprising:

- (a) an insulating material having a first surface;
- (b) a defective pattern of conductors on the first surface;
- (c) a wire bond slot forming an opening through the substrate extending from the first surface to a second surface; and
- (d) a cover member attached to the substrate on the second surface so as to cover at least a portion of the wire bond slot, wherein the cover member does not comprise a functional die, and wherein the cover member covers at least 70% of the opening formed by the wire bond slot.